JSCJ

MSDS Report

Report NO.: M000004000134

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC50P03
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition		CAS No.	% of weight	% of weight total
Wafer	Silicon		7440-21-3	100.00%	4.63%
Lead Frame	Copper		7440-50-8	97.52%	34.28%
	Iron		7439-89-6	2.35%	
	P		7723-14-0	0.08%	
	Plating Ag		7440-22-4	0.05%	
Solder	Lead		7439-92-1	85.00%	3.66%
	Tin		7440-31-5	4.35%	
	Silver		7440-22-4	2.15%	
	Butanediol mixture		107-88-0	7.50%	
	Modified castor oil		61788-85-0	1.00%	
Aluminum Ribbon	Aluminum		7429-90-5	100.00%	2.43%
Wire	AuPdCu	Copper	7440-50-8	97.95%	
		Palladium	7440/5/3	1.80%	
		Gold	7440-57-5	0.25%	
Mold Compound	Silica		60676-86-0	82.00%	52.59%
	Epoxy Resin		85954-11-6	10.00%	
	Phenol Resin		26834-02-6	7.50%	
	Carbon black		1333-86-4	0.50%	
Plating	Tin		7440-31-5	99.99%	2.41%
	Other		/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.